

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_  
PRODUCT 产品: SAW RESONATOR  
MODEL NO 型号: HDR431.7MS-F11A  
PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_  
APPROVED 批准: \_\_\_\_\_ DATE 日期: 2010-8-26

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited

更改历史记录  
History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

## 1. SCOPE

This specification shall cover the characteristics of 1-port SAW resonator with used for remote-control security.

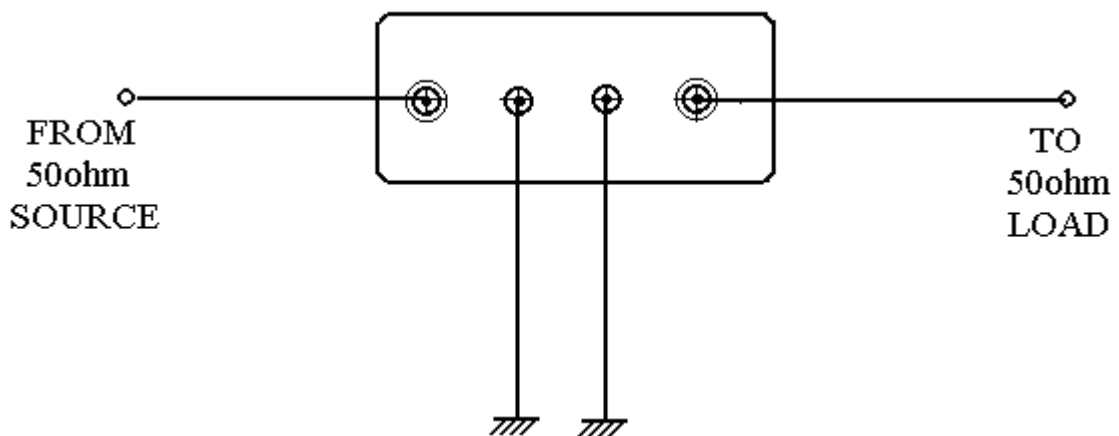
## 2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

### 2.2 Electronic Characteristics

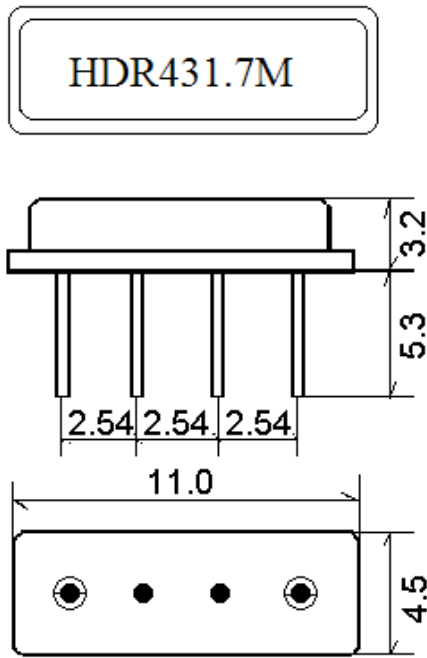
Item		Unites	Minimum	Typical	Maximum
Center Frequency		MHz	431.625	431.700	431.775
Insertion Loss		dB		1.3	2.5
Quality Factor Unload Q				11500	
50 Ω Loaded Q				983	
Temperature Stability	Turnover Temperature	°C	10	25	40
	Freq.temp.Coefficient	ppm/°C <sup>2</sup>		0.032	
Frequency Aging		ppm/yr		<± 10	
DC. Insulation Resistance		MΩ	1.0		
RF Equivalent RLC Model	Motional Resistance R1	Ω		20	26
	Motional Inductance L1	μ H		73.3	
	Motional Capacitance C1	fF		1.85	
Transducer Static Capacitance		pF		1.9	

## 3. TEST CIRCUIT

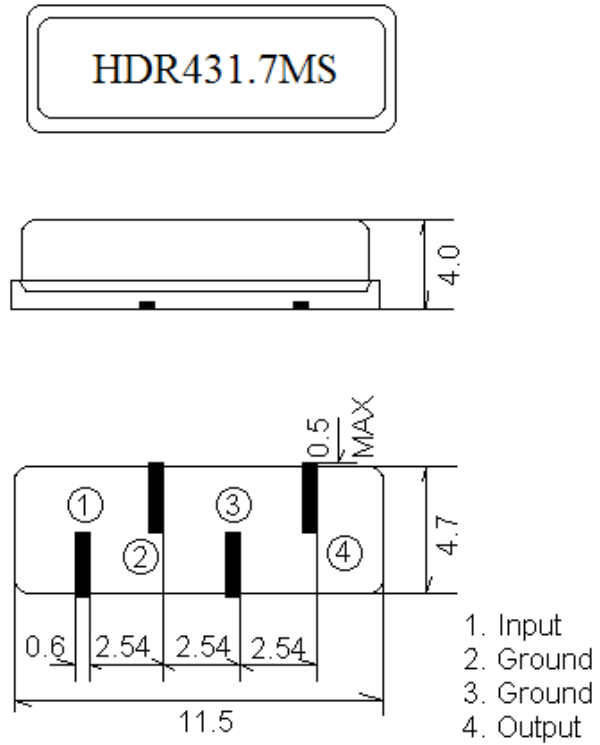


**4. DIMENSION**

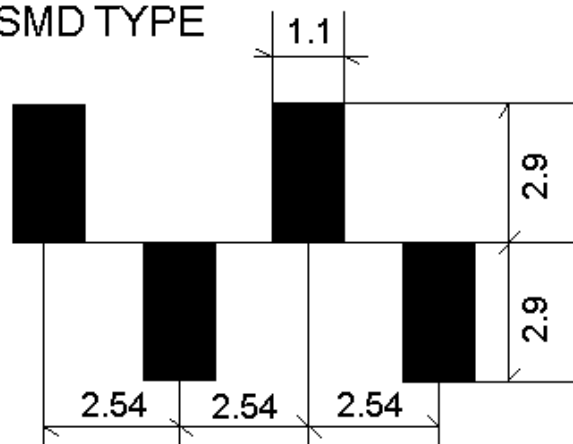
■ **DIP TYPE:**



■ **SEMI-SMD TYPE:**



■ **Recommended layout of PCB(MM) (Tolerance  $\pm 0.2$ MM) for Semi-SMD TYPE**



## 5. ENVIRONMENTAL CHARACTERISTICS

### 5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the resonator into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

### 5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

### 5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

### 5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C  $\pm$ 10°C for 10 $\pm$ 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

### 5-5 Solderability

Subject the device terminals into the solder bath at 245°C  $\pm$ 5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

### 5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

### 5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

## 6. REMARK

### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.